

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

SEKO, Toshiharu

Atty. Ref.: 925-214

Serial No. unknown

Group:

Filed: October 12, 2001

Examiner:

For: TAPE FOR CHIP ON FILM AND SEMICONDUCTOR THEREWITH

* * * * *

October 12, 2001

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

IN THE CLAIMS

Please substitute the following amended claim 18 for the corresponding claim 18 previously presented. A copy of the amended claim 18 showing current revisions is attached.

099506-1001
"TOP OF"

18. A semiconductor device comprising a semiconductor element mounted on the tape for chip on film as defined in Claim 1 and sealed with resin.

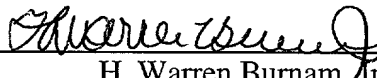
SEKO, Toshiharu
Serial No. unknown

REMARKS

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page/s is/are captioned "**Version With Markings To Show Changes Made.**"

Respectfully submitted,

NIXON & VANDERHYE P.C.

By: 
H. Warren Burnam, Jr.
Reg. No. 29,366

HWB:ecb
1100 North Glebe Road, 8th Floor
Arlington, VA 22201-4714
Telephone: (703) 816-4000
Facsimile: (703) 816-4100

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

18. A semiconductor device comprising a semiconductor element mounted on the tape
for chip on film as defined in ~~any one of~~ Claims 1 to 17 and sealed with resin.